

SOT1921-1

HQFN24, thermal enhanced quad flat package, no leads, step-cut wettable flank, 24 terminals, 0.8 mm pitch, 6 mm x 6 mm x 1.98 mm body

8 February 2019

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HQFN24
Package style descriptive code	HQFN (thermal enhanced quad flatpack; no leads)
Mounting method type	S (surface mount)
Issue date	25-12-2018
Manufacturer package code	98ASA01071D

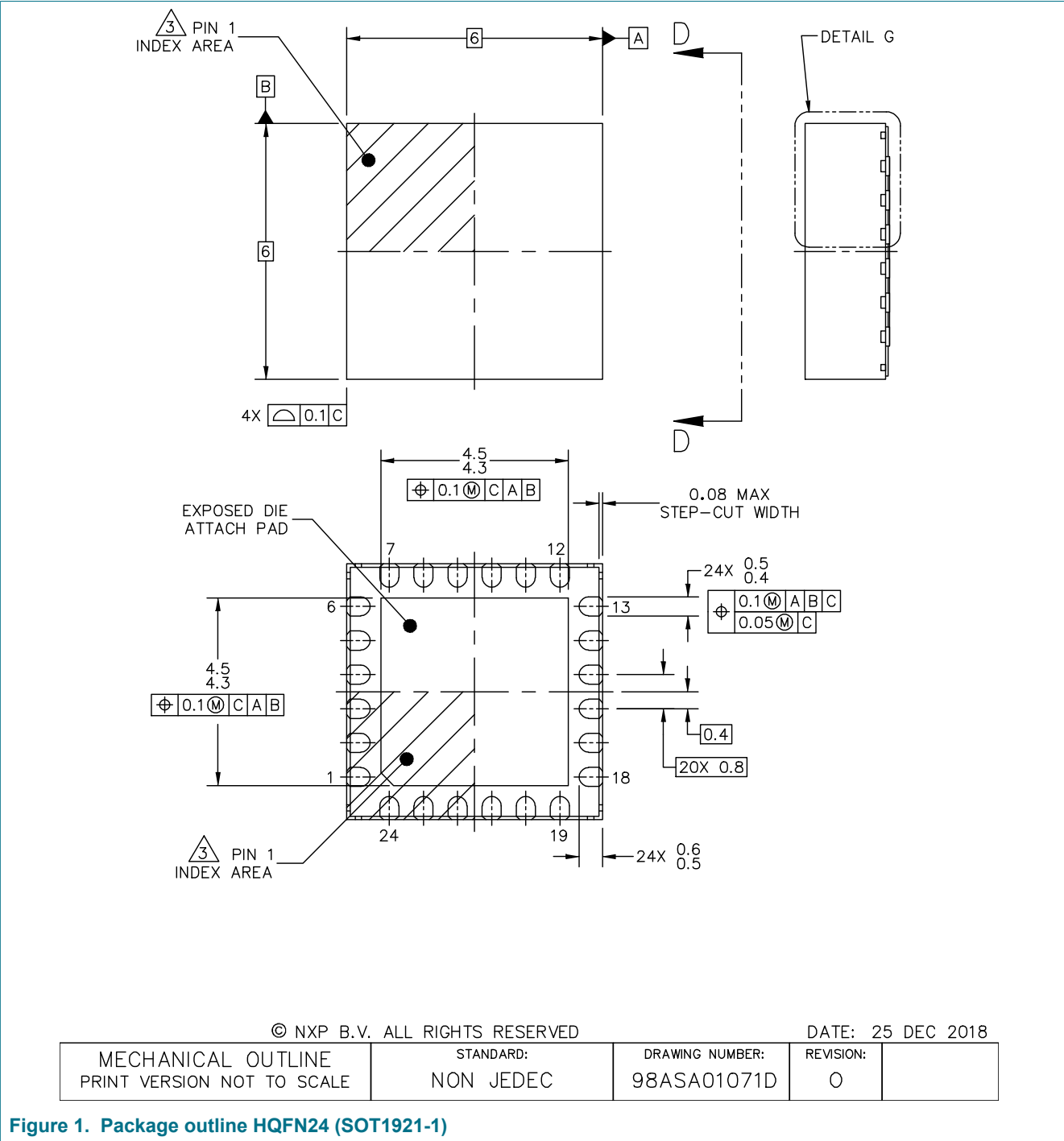
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	6	-	mm
package width	-	6	-	mm
package height	-	1.98	-	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	24	-	

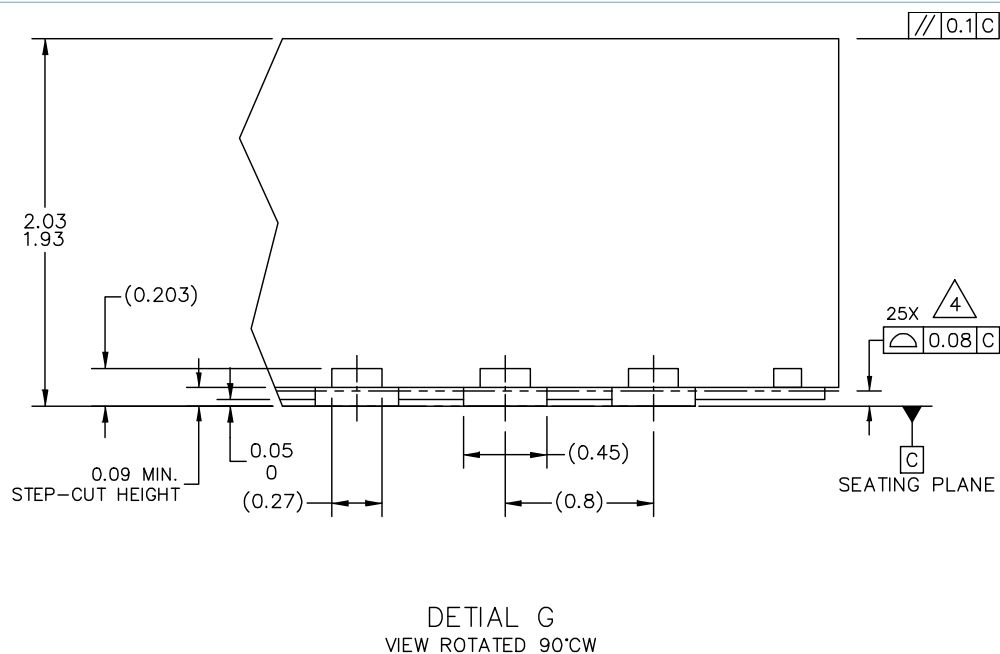


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2 Package outline



HQFN24, thermal enhanced quad flat package, no leads, step-cut wettable flank, 24 terminals, 0.8 mm pitch, 6 mm x 6 mm x 1.98 mm body



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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01071D	REVISION: 0	

Figure 2. Package outline detail HQFN24 (SOT1921-1)

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- NOTES:
- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
 - 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
 - 3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
 - 4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG AND CORNER NON-FUNCTIONAL PADS.
 - 5. MIN. METAL GAP SHOULD BE 0.2 MM.

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Figure 3. Package outline note HQFN24 (SOT1921-1)

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3 Legal information

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